

Laser processing and engineering expertise that delivers breakthrough levels of productivity and yield.

ESI's most advanced HDI microvia drilling solution for precision processing of your HDI, SLP and ICP applications. The Geode™ laser drilling system combines a powerful CO<sub>2</sub> laser with a set of control capabilities that leverage ESI's decades of laser-material interaction experience and application expertise to help you innovate and stay ahead.



## Throughput



### Hypersonix

Sound waves modify laser pulses to improve via quality and increase throughput.



### AcceleDrill

Uses sound waves to distribute light to drill different via toolings without optics path adjustments (no downtime).

## Footprint



### LiteDesign

Compact and lightweight system architecture allows for more installation flexibility and reduces production footprint.



### UpTime

Easy-access design improves serviceability and decreases maintenance and service downtime.